



# **SPECIFICATION**

(Reference sheet)

· Supplier : Samsung electro-mechanics · Samsung P/N : CL32B106KBJZW6E

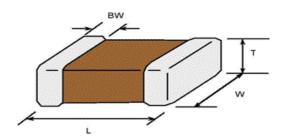
· Product : Multi-layer Ceramic Capacitor · Description : CAP, 10uF, 50V, ±10%, X7R, 1210

### A. Samsung Part Number

<u>CL</u> <u>32</u> <u>B</u> <u>106</u> <u>K</u> <u>B</u> <u>J</u> <u>Z</u> <u>W</u> <u>6</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor					
2	Size	1210 (inch code)	L: 3.20	± 0.30 mm	W: 2.50 ± 0.20 mm		
3	Dielectric	X7R	8	Inner electrode	Ni		
4	Capacitance	10 uF		Termination	Soft termination		
<b>⑤</b>	Capacitance	±10 %		Plating	Sn 100% (Pb Free)		
	tolerance		9	Product	Industrial (Network,Power,etc)		
6	Rated Voltage	50 V	10	Special	Higher bending strength		
7	Thickness	$2.50 \pm 0.20 \text{ mm}$	11)	Packaging	Embossed Type, 7" reel		

#### **B. Structure & Dimension**



Samsung P/N	Dimension(mm)					
Samsung F/N	L	W	Т	BW		
CL32B106KBJZW6E	3.20 ± 0.30	2.50 ± 0.20	2.50 ± 0.20	0.60 ± 0.30		

#### C. Samsung Reliablility Test and Judgement Condition

Capacitance       Within specified tolerance       1 kHz ±10% / 1.0±0.2Vrms         Tan δ (DF)       0.1 max.       *A capacitor prior to measuring the capacitance is h treated at 150 °C +0/-10 °C for 1hour and maintained is ambient air for 24±2 hours.         Insulation       10,000Mohm or 100Mohm×μF       Rated Voltage 60~120 sec         Resistance       Whichever is smaller       Rated Voltage 60~120 sec         Appearance       No abnormal exterior appearance       Microscope (×10)         Withstanding       No dielectric breakdown or mechanical breakdown       250% of the rated voltage         Temperature       X7R         Characteristics       (From -55 °C to 125 °C, Capacitance change should be within ±15%)         Adhesive Strength of Termination       No peeling shall be occur on the terminal electrode       500g·f, for 10±1 sec.         Bending Strength       Capacitance change: within ±12.5%       Bending to the limit (3mm) with 1.0mm/sec.         Solderability       More than 75% of terminal surface is to be soldered newly       SnAg3.0Cu0.5 solder 245±5°C, 3±0.3sec. (preheating: 80~120°C for 10~30sec.)         Resistance to       Capacitance change: within ±7.5%       Solder pot: 270±5°C, 10±1sec.         Soldering Heat       Tan δ, IR: initial spec.       Amplitude: 1.5mm From 10Hz to 55Hz (return: 1min.)			
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Resistance to Capacitance change : within $\pm 7.5\%$ Solder pot : $270\pm 5^{\circ}$ C, $10\pm 1$ sec.  Vibration Test Capacitance change : within $\pm 5\%$ Amplitude : $1.5$ mm From $10$ Hz to $55$ Hz (return : $1$ min.)	1		
Soldering HeatTan $\delta$ , IR : initial spec.Amplitude : 1.5mmVibration TestCapacitance change : within $\pm$ 5%Amplitude : 1.5mmTan $\delta$ , IR : initial spec.From 10Hz to 55Hz (return : 1min.)			
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2hours × 3 direction (x, y, z)			
Moisture Capacitance change: within ±12.5% With rated voltage			
ResistanceTan δ : 0.125 max $40\pm2^{\circ}$ C, 90~95%RH, 500+12/-0hrsIR : 500Mohm or 12.5Mohm × $\mu$ FWhichever is smaller			
High Temperature Capacitance change: within ±12.5% With 150% of the rated voltage			
Resistance       Tan δ : 0.125 max       Max. operating temperature			
IR : 1,000Mohm or 25Mohm ×			
Temperature Capacitance change: within ±7.5% 1 cycle condition			
Cycling Tan $\delta$ , IR: initial spec. Min. operating temperature $\rightarrow$ 25°C			
→ Max. operating temperature → 25°C			
5 cycle test			

X The reliability test condition can be replaced by the corresponding accelerated test condition.

#### D. Recommended Soldering method:

Reflow ( Reflow Peak Temperature :260±5°C, 30sec)



Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.

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The products listed in this Specification sheet are **NOT** designed and manufactured for any use and applications set forth below.

Please note that any misuse of the products deviating from products specifications or information provided in this Spec sheet may cause serious property damages or personal injury.

We will **NOT** be liable for any damages resulting from any misuse of the products, specifically including using the products for high reliability applications as listed below.

If you have any questions regarding this 'Limitation of Use and Application', you should first contact our sales personnel or application engineers.

- ① Aerospace/Aviation equipment
- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- 4 Military equipment
- ⑤ Disaster prevention/crime prevention equipment
- 6 Power plant control equipment
- Atomic energy-related equipment
- Undersea equipment
- Traffic signal equipment
- Data-processing equipment
- ## Electric heating apparatus, burning equipment
- Safety equipment
- ® Any other applications with the same as or similar complexity or reliability to the applications